

Abstract of the Disclosure

The present invention relates to an alignment mark for use in a wafer alignment and a method for fabricating the same. The alignment mark for use in the wafer alignment includes: a first mark formed on a semiconductor layer; a second mark formed adjacent to the first mark on the semiconductor layer; and a concave part formed between the first mark and the second mark by etching a partial portion of the semiconductor layer, wherein the alignment mark is used to align a wafer by detecting a zeroth order diffract light reflected from a sloped surface formed because of a difference in height between the concave part and the first or second mark.